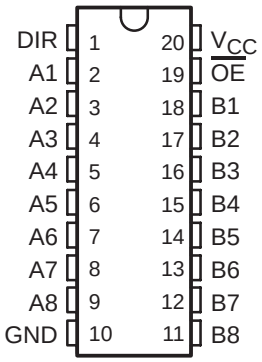
- **BiCMOS Design Significantly Reduces I_{CCZ}**
- **3-State True Outputs Drive Bus Lines Directly**
- **High-Impedance State During Power Up and Power Down**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015**
- **Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic 300-mil DIPs (N)**

DW OR N PACKAGE
(TOP VIEW)



description

This octal bus transceiver is designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so the buses are effectively isolated.

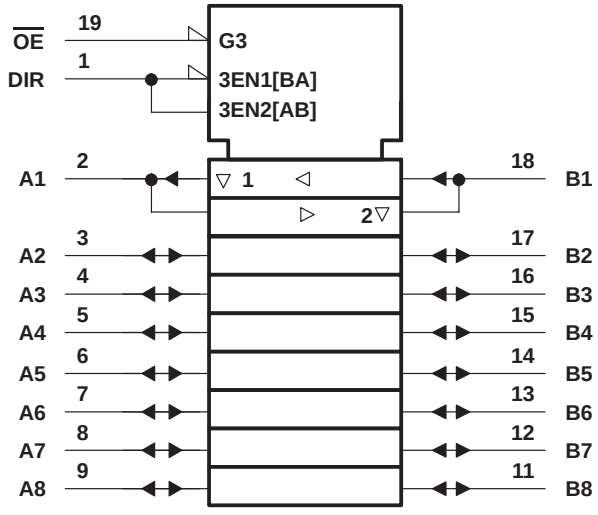
The outputs are in a high-impedance state during power up and power down while the supply voltage is less than approximately 3 V.

The SN64BCT245 is characterized for operation from −40°C to 85°C and 0°C to 70°C.

FUNCTION TABLE

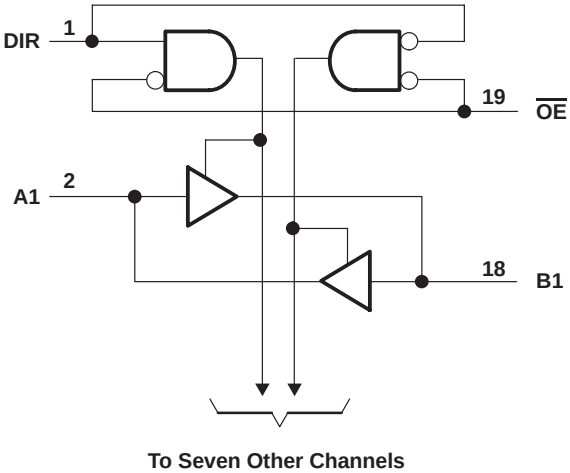
INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . − 0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . − 0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O . . . . . − 0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O . . . . . − 0.5 V to V_{CC}
Current into any output in the low state . . . . . 128 mA
Operating free-air temperature range . . . . . − 40°C to 85°C
Storage temperature range . . . . . − 65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage				0.8	V
I_{IK}	Input clamp current				−18	mA
I_{OH}	High-level output current	A1−A8			−3	mA
		B1−B8			−15	
I_{OL}	Low-level output current	A1−A8			24	mA
		B1−B8			64	
T_A	Operating free-air temperature		−40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA				−1.2	V
V_{OH}	Any A	V_{CC} = 4.5 V	I_{OH} = −1 mA		2.5	3.4		V
	Any A or B		I_{OH} = −3 mA		2.4	3.3		
	Any B		I_{OH} = −15 mA		2	3.1		
V_{OL}	Any A	V_{CC} = 4.5 V	I_{OL} = 24 mA			0.35	0.5	V
	Any B		I_{OL} = 64 mA			0.42	0.55	
I_{OZ}	Power up	V_{CC} = 0 to 2.3 V	V_O = 2.7 V	$\overline{OE}$ at 0.8 V			70	µA
			V_O = 0.5 V				−0.65	mA
	Power down	V_{CC} = 1.8 V to 0	V_O = 2.7 V	$\overline{OE}$ at 0.8 V			70	µA
			V_O = 0.5 V				−0.65	mA
I_I‡	A and B	V_{CC} = 5.5 V,	V_I = 5.5 V				1	mA
	DIR and $\overline{OE}$						0.1	
I_{IH}‡	A and B	V_{CC} = 5.5 V,	V_I = 2.7 V				70	µA
	DIR and $\overline{OE}$						20	
I_{IL}	A and B	V_{CC} = 5.5 V,	V_I = 0.5 V				−0.65	mA
	DIR and $\overline{OE}$						−1.2	
I_{OS}§	Any A	V_{CC} = 5.5 V,	V_O = 0		−60		−150	mA
	Any B				−100		−225	
I_{CCH}	A-to-B	V_{CC} = 5.5 V				36	57	mA
I_{CCL}	A-to-B	V_{CC} = 5.5 V				57	90	
I_{CCZ}		V_{CC} = 5.5 V				10	15	
C_i	$\overline{OE}$ and DIR	V_{CC} = 5 V,	V_I = 2.5 V or 0.5 V			7		pF
C_{io}	A to B	V_{CC} = 5 V,	V_I = 2.5 V or 0.5 V			9		pF
	B to A					12		

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = 25°C		V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω				UNIT
					T_A = −40°C to 85°C		T_A = 0°C to 70°C		
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	6	1	7.2	1	7	ns
t_{PHL}			1.5	6.6	1.5	7.6	1.5	7	
t_{PZH}	$\overline{OE}$	A or B	1.5	9.4	1.5	11.2	1.5	10.9	ns
t_{PZL}			1.5	10.2	1.5	11.8	1.5	11.6	
t_{PHZ}	$\overline{OE}$	A or B	1.5	8.3	1.5	9.7	1.5	9.3	ns
t_{PLZ}			1.5	7.8	1.5	9.6	1.5	9.1	

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN64BCT245DW	Active	Production	SOIC (DW) | 20	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6BCT245
SN64BCT245DW.A	Active	Production	SOIC (DW) | 20	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6BCT245

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

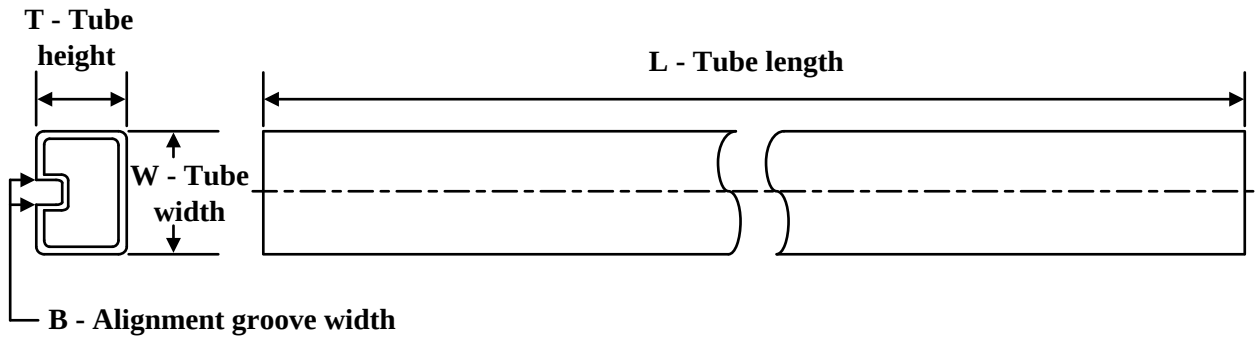
(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

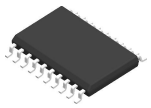
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN64BCT245DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN64BCT245DW.A	DW	SOIC	20	25	507	12.83	5080	6.6

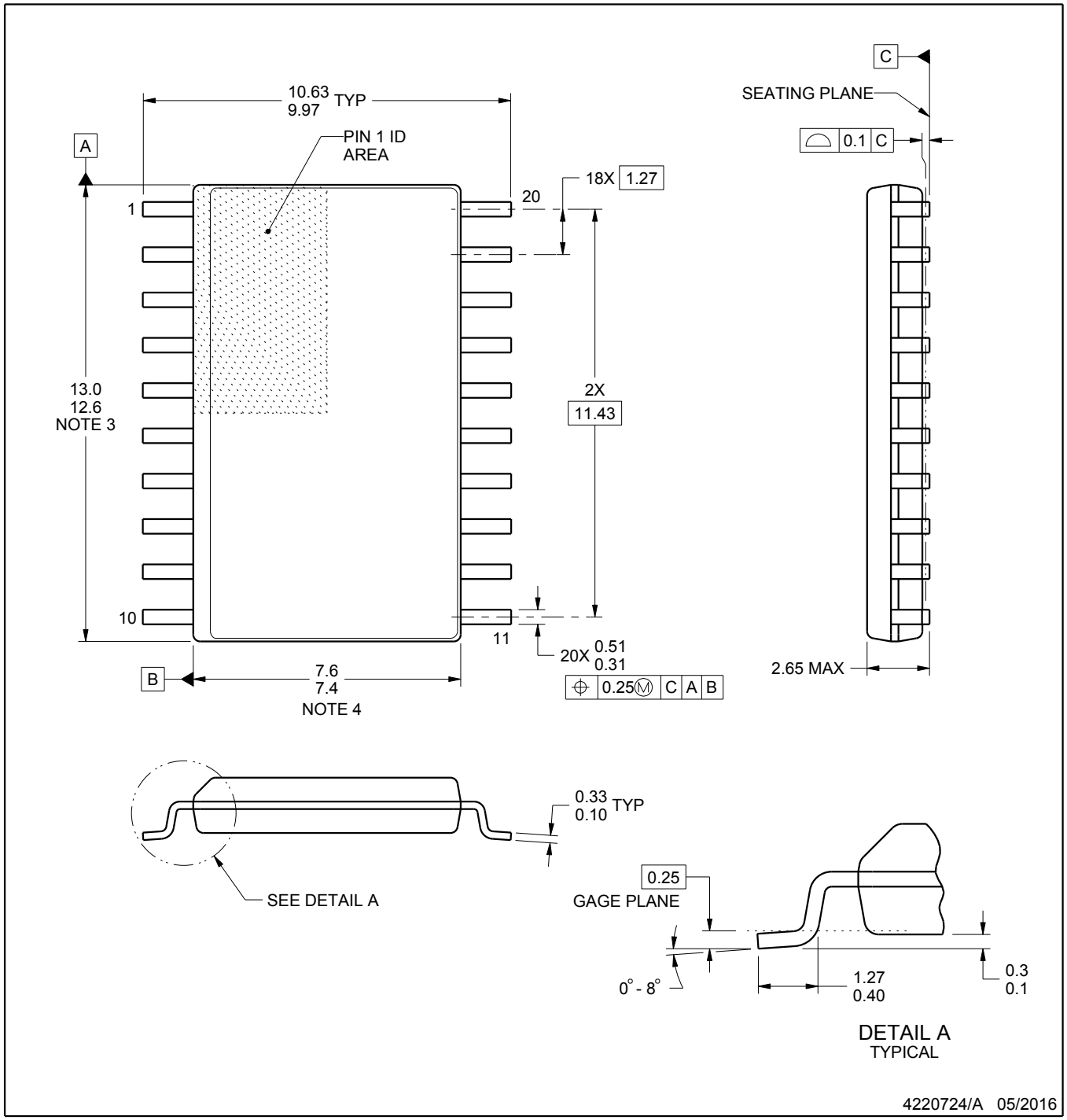


PACKAGE OUTLINE

DW0020A

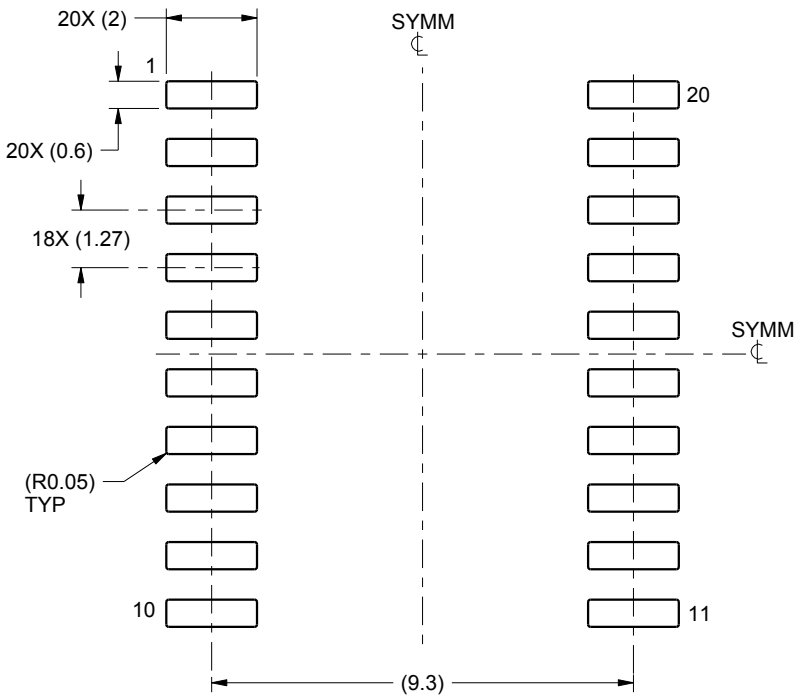
SOIC - 2.65 mm max height

SOIC

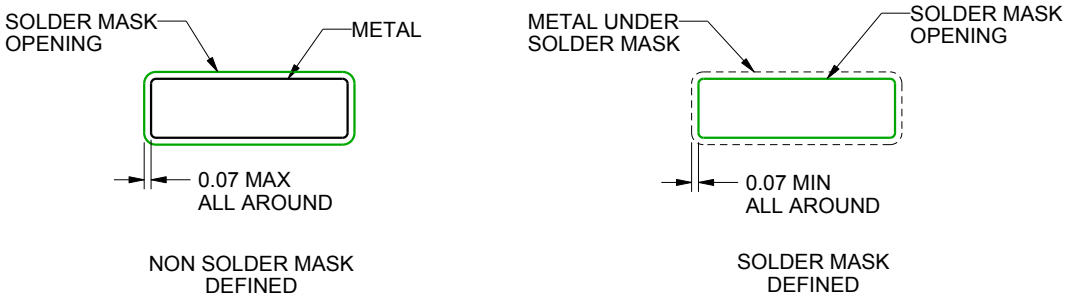


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

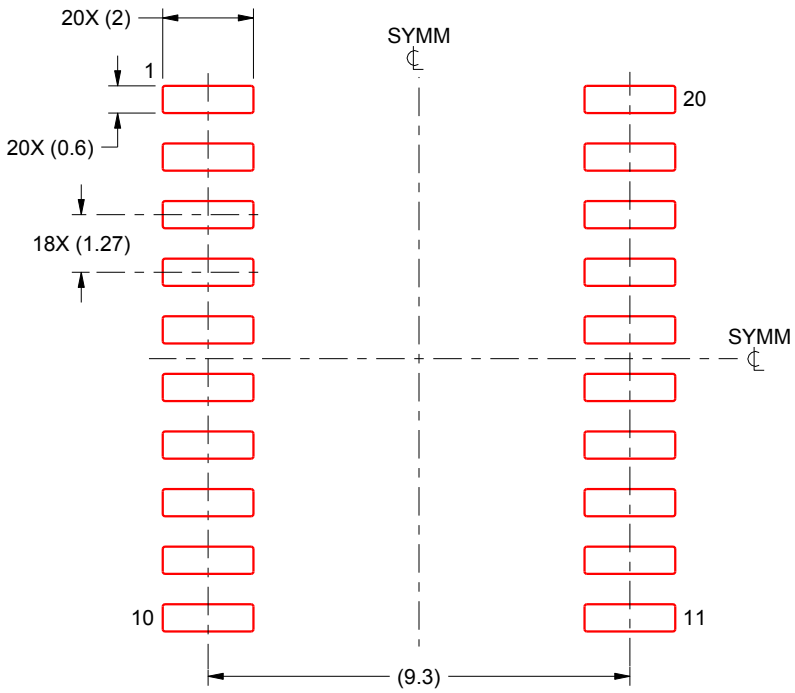


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale, TI’s General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Last updated 10/2025